

## **LISTING OF THE CLAIMS**

**The present listing of claims replaces all prior versions.**

**Claims 1 –7. (Cancelled)**

**Claim 8. (Previously Presented)** Dip soldering apparatus applying solder to component leads extending downwardly from a printed circuit board, said apparatus comprising:

a reservoir for molten solder;

an elongate plate provided in the reservoir and positioned at a surface of the molten solder; and

a holder supporting said printed circuit board, said holder and said reservoir defining one of a first and a second condition, wherein, said first condition said printed circuit board is positioned away from said reservoir and in said second condition said printed circuit board is positioned above said reservoir with said component leads extending at least partially into said molten solder;

wherein said plate has an upwardly facing edge and side surfaces extending downwards from the plate edge, the plate being positioned and dimensioned in said second condition to fit between adjacent component leads so that said adjacent component are disposed on each side of the plate edge respectively and the plate surface being of a material which is wetted by the molten solder

**Claim 9. (Currently Amended)** Dip soldering apparatus applying solder to the leads of an electronic component, said apparatus comprising:

a nozzle having an outlet through which solder is flowed in use; and

a component holder supporting said component, said holder ~~and said nozzle~~ being movable between a raised condition in which said component is remote from said nozzle and a lowered condition in which leads to be soldered are dipped into the solder surface at the nozzle outlet;

wherein the nozzle includes a member provided at the nozzle outlet and having a surface which is wetted by the solder, the surface being positioned so as to be straddled by two adjacent leads;

wherein the member is positioned so as to project through the solder surface as said component holder is moved toward said raised condition and as the leads are withdrawn from the solder [[:]]

~~wherein means is provided to separate said holder and said nozzle to effect withdrawal of the leads from the solder.~~

**Claims 10 –18. (Cancelled)**

**Claim 19. (Previously Presented)** The apparatus of claim 9, wherein the member has a honeycomb structure.

**Claim 20. (Previously Presented)** Dip soldering apparatus for applying solder to the leads of an electronic component comprising:

a component holder supporting said component;

a nozzle having an outlet through which solder is flowed in use to form a solder surface, and being movable between a first position below and separated from said component and a second position in which said leads to be soldered are dipped into the solder surface at the nozzle outlet, wherein the nozzle includes a member provided at the nozzle outlet and having a surface which is wetted by the solder, the surface being positioned so as to be straddled by two adjacent leads; and

means for selectively lowering the solder surface in order to effect withdrawal of the leads from the solder;

wherein said member is movable relative to said solder surface.

#### **Claims 21 –24. (Cancelled)**

**Claim 25. (Currently Amended)** Dip soldering apparatus comprising a component holder supporting a component with leads, a nozzle having a raised position and a lowered position and having an outlet through which solder is flowed in use, leads of the component to be soldered being dipped into the solder surface at the nozzle outlet when said nozzle is in said raised position, wherein the nozzle includes a member provided at the nozzle outlet and having a surface which is wetted by the solder, the surface being positioned so as to be straddled by two adjacent leads to be soldered when said nozzle is in said raised position;

said apparatus further including ~~means~~ a nozzle lowering member for lowering said nozzle to said lowered position ~~the solder surface~~, in order to effect withdrawal of

the leads from the solder.

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**Claim 26. (Previously Presented)** The apparatus of claim 25, wherein said member is disposed below the level of the solder surface as the solder flows through the nozzle outlet.

**Claim 27. (Previously Presented)** The apparatus of claim 25, wherein said member is movable relative to the solder surface.

**Claim 28. (Previously Presented)** The apparatus of claim 25, wherein said member is positioned for projecting through the solder surface as the leads are withdrawn from the solder.

**Claim 29. (Previously Presented)** Dip soldering apparatus comprising:

- a holder supporting a component with leads to be soldered;
- a reservoir for molten solder;
- an elongate plate provided in the reservoir and positioned at a surface of the molten solder, the plate having an upwardly facing edge and side surfaces extending downwards from the plate edge, the plate being positioned and dimensioned so that adjacent component leads to be soldered pass to each side of the plate edge and the plate surface being of a material which is wetted by the molten solder; and
- means for lowering the solder surface away from said holder for effecting

withdrawal of the component leads from the solder;

wherein said plate is movable relative to the solder surface.

**Claims 30-36. (Cancelled)**